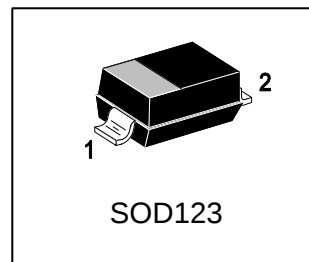


S-LBAT46T1G

Schottky Power Rectifier

1. FEATURES

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount device
- Lead and Mounting Surface Temperature for Soldering Purposes:
260°C Max. for 10 Seconds
- We declare that the material of product compliance with
RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring
unique site and control change requirements; AEC-Q101
qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
S-LBAT46T1G	Z46	3000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Repetitive peak reverse voltage	VRRM	100	V
Continuous forward current	IF	150	mA
Surge Non repetitive forward current	IFSM	1	A
Power Dissipation	PD	250	mW
Storage temperature range	Tstg	-55~+150	°C
Maximum operating junction temperature(Note 1)	Tj	150	°C
Maximum soldering temperature(Note 1)	TL	260	°C

1. Pulse test: tp = 380 μs, δ < 2 %

4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Thermal resistance from junction to ambient	RθJA	500	°C/W

2. On epoxy printed circuit board with recommended pad layout

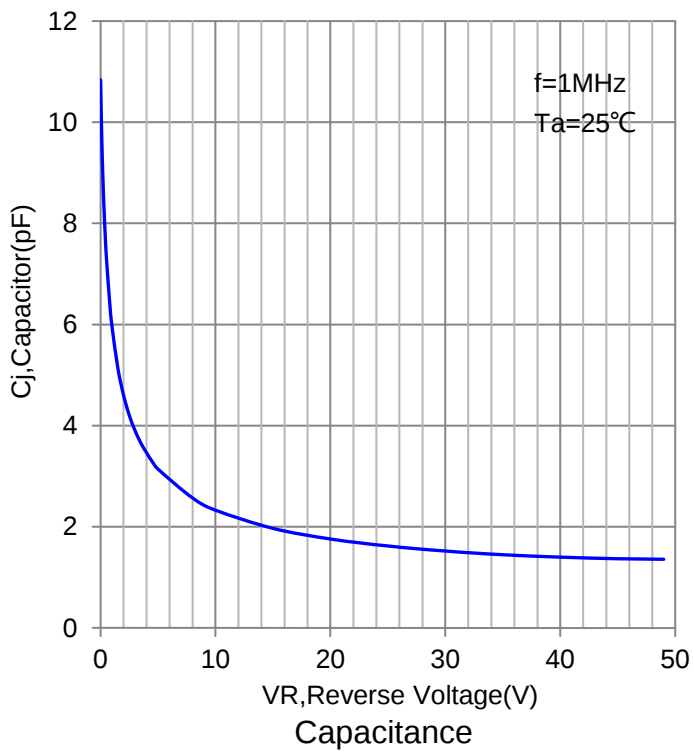
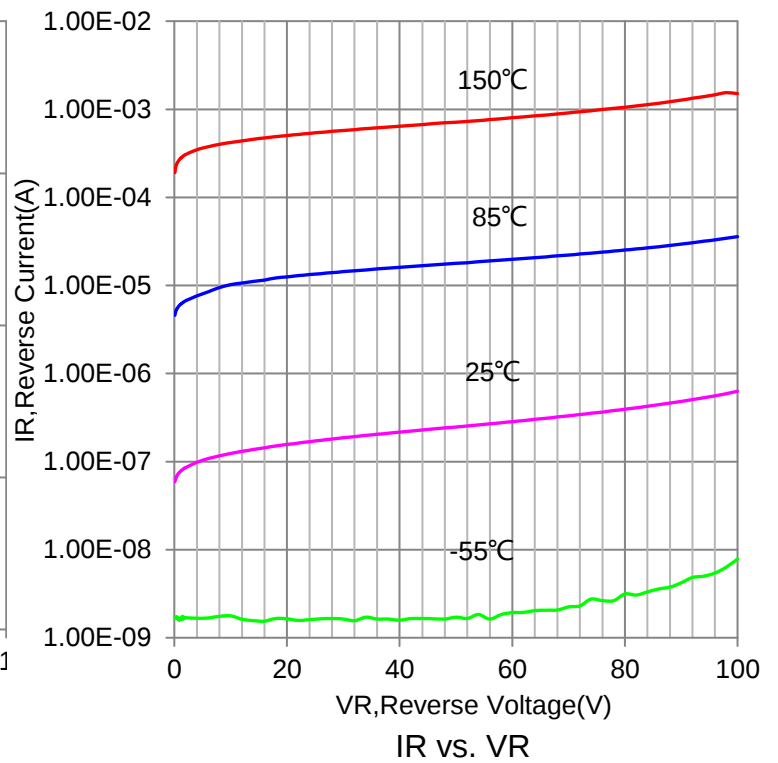
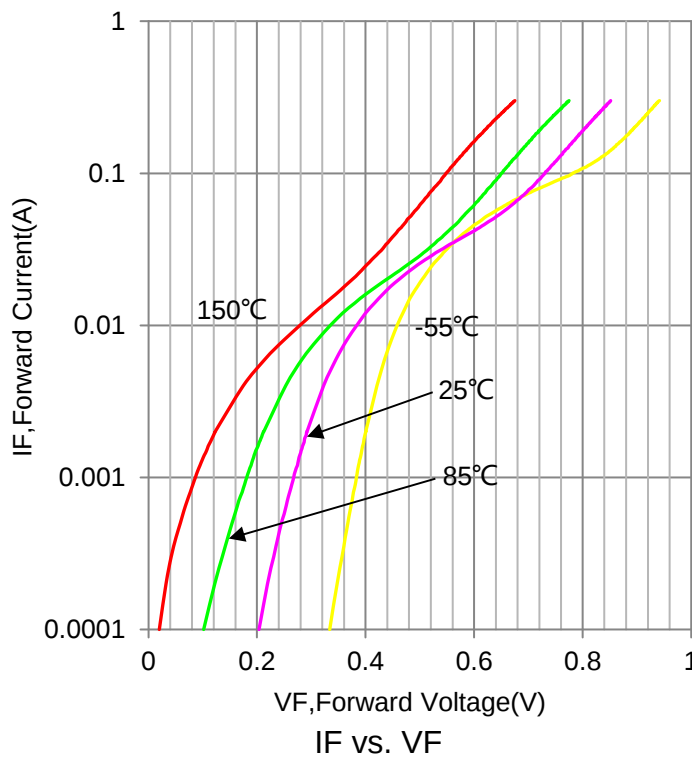
5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Leakage Current(Tj = 25°C) (VR=1.5V) (VR=10V) (VR=50V) (VR=75V)	IR(Note 3)	-	-	0.5	μA
		-	-	0.8	
		-	-	2	
		-	-	5	
Reverse Leakage Current(Tj = 60°C) (VR=1.5V) (VR=10V) (VR=50V) (VR=75V)		-	-	5	
		-	-	7.5	
		-	-	15	
		-	-	20	
Forward Voltage(Tj = 25°C) (IF=0.1mA) (IF=10mA) (IF=250mA)	VF	-	-	0.25	V
		-	-	0.45	
		-	-	1	
		-	-	-	
Diode Capacitance (VR =0V, f=1.0MHz) (VR =1V, f=1.0MHz)	Cd	-	11	-	pF
		-	6	-	

3. Pulse test: tp = 5 ms, δ < 2 %

4. Pulse test: tp = 380 μs, δ < 2 %

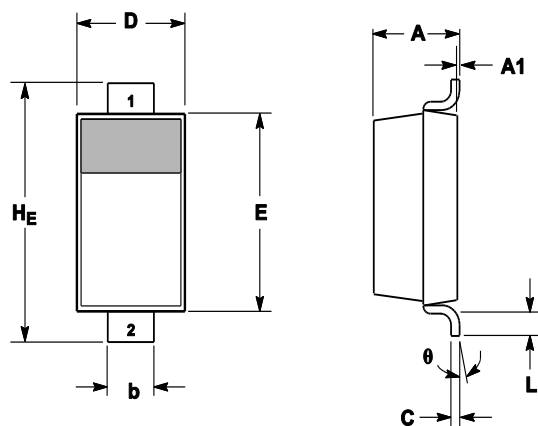
6.ELECTRICAL CHARACTERISTICS CURVES



7.OUTLINE AND DIMENSIONS

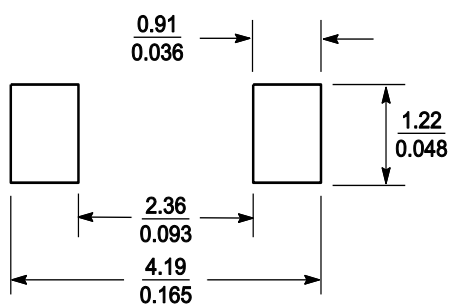
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
c	---	---	0.15	---	---	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
H _E	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25	---	---	0.010	---	---
θ	0°	---	10°	0°	---	10°

8.SOLDERING FOOTPRINT



SCALE 10:1 (mm / inches)

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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